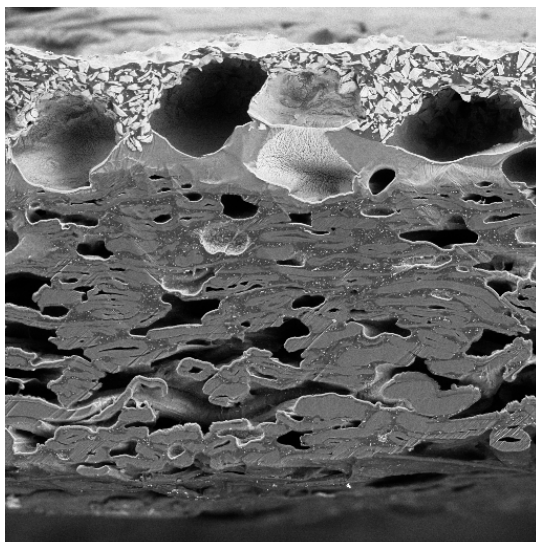


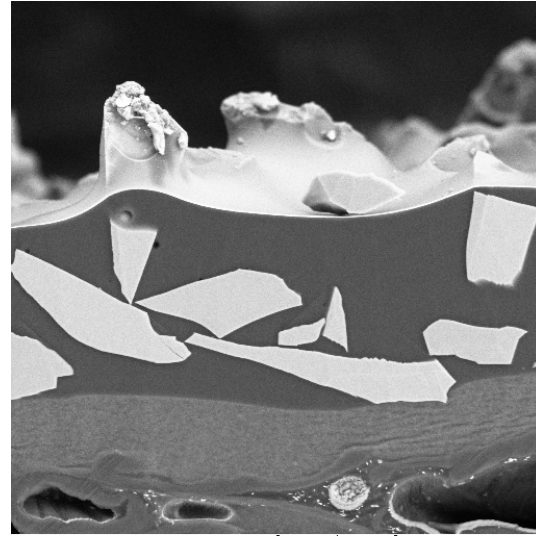
SEM MAG: 495 x DET: BSE
HV: 10.0 kV DATE: 05/14/10
VAC: HiVac Device: VEGA 5130
100 um Vega ©Tescan CZ



SEM MAG: 484 x DET: BSE
HV: 10.0 kV DATE: 05/18/10
VAC: HiVac Device: VEGA 5130
100 um Vega ©Tescan CZ



SEM MAG: 602 x DET: BSE
HV: 10.0 kV DATE: 05/10/10
VAC: HiVac Device: VEGA 5130
100 um Vega ©Tescan CZ



SEM MAG: 1,584 x DET: BSE
HV: 10.0 kV DATE: 05/17/10
VAC: HiVac Device: VEGA 5130
20 um Vega ©Tescan CZ

Application Note

Leica EM TIC020 – Cross Section of SiC paper

Market: Paper industry, Metallographic industry
Companies (e.g.): Bühler, Struers, Akasel,...

Living up to Life

Leica EM TIC020 Application Note

Cross Section of SiC paper

Goal:

- Cross section of SiC paper

Process description (benchmark values for this particular sample):

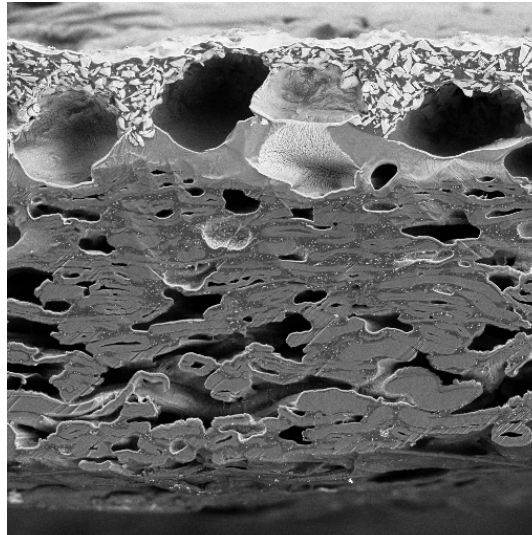
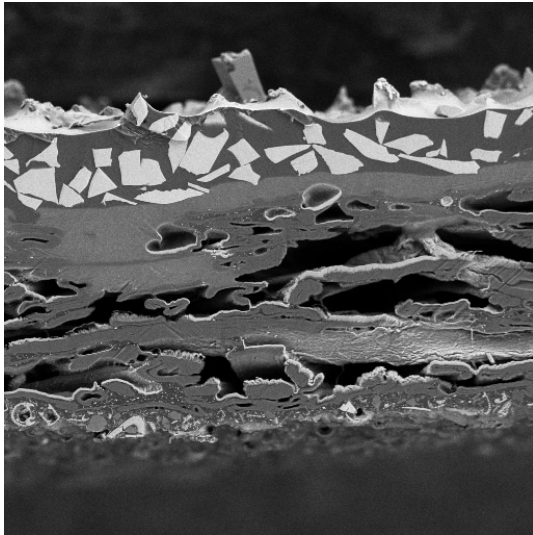
Mechanical pre-preparation:

Parameter	
Acceleration voltage	7kV
Gun current	2.6mA
Milling time	3h
Cut depth	200µm

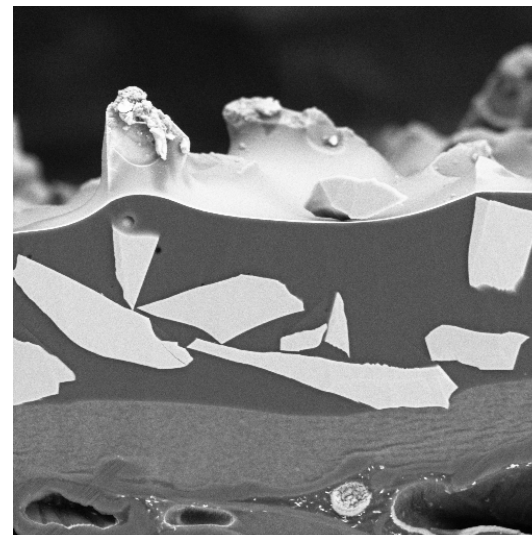
Results:

- Perfect cross section of the SiC paper
- Information about the abrasive particles (size, shape, orientation and distribution)

Wolfgang Grünewald, Leica Microsystems
Wolfgang.Gruenewald@leica-microsystems.com



Cross section of 800 grit (left) and 2400 grit (right) SiC paper



Cross section of 1200 grit SiC paper